

## 2.5V - 5.5V Input / 1A Output / 0.8V - 5.5V Output

### DESCRIPTION

The VDMM 171010501 Magl<sup>3</sup>C power module provides a fully integrated DC-DC power supply including the switching regulator IC with integrated MOSFETs, controller, compensation and shielded inductor in one package.

The 171010501 offers high efficiency and delivers up to 1A of output current. It operates with an input voltage from 2.5V to 5.5V and is designed for a small solution size.

The module maintains high efficiency throughout the output current range by automatically transitioning between modes of operation based on the load demands.

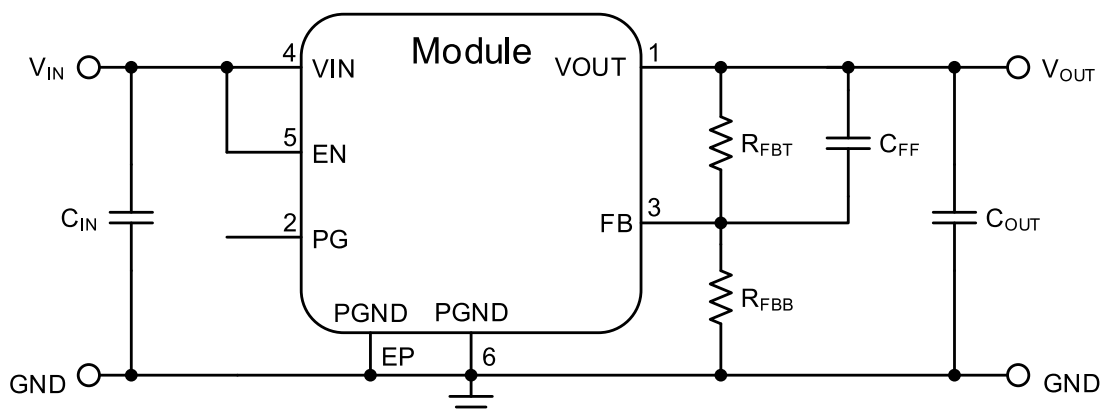
The 171010501 is available in an LGA-6EP package (3.2 x 2.5 x 1.55mm).

This power module has integrated protection circuitry that guards against thermal overstress with thermal shutdown and protects against electrical damage using overcurrent, short-circuit and undervoltage protections.

### TYPICAL APPLICATIONS

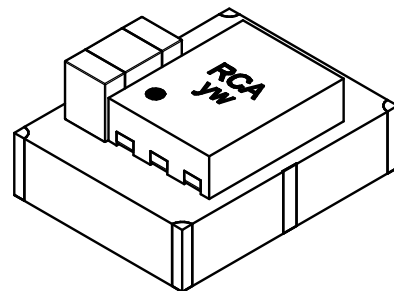
- Point of load power supply for low power systems
- Replacement of linear regulators
- DSP and FPGA power supply auxiliary voltages
- Portable instruments
- Battery powered equipment

### TYPICAL CIRCUIT DIAGRAM



### FEATURES

- Peak efficiency up to 96%
- Input voltage range: 2.5V to 5.5V
- Typical quiescent current: 20 $\mu$ A
- Output voltage range: 0.8V to 5.5V
- Current capability up to 1A
- Constant on-time control
- Synchronous operation
- Fixed switching frequency: 4MHz
- Power good indicator
- Embedded soft-start
- Undervoltage lockout (UVLO)
- Cycle-by-cycle current limit
- Short-circuit protection
- Thermal shutdown
- Ambient temp. range: -40°C to 85°C
- Junction temp. range: -40°C to 125°C
- RoHS and REACH compliant
- Complies with EN55032 class B radiated emissions standard



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## 1 PINOUT

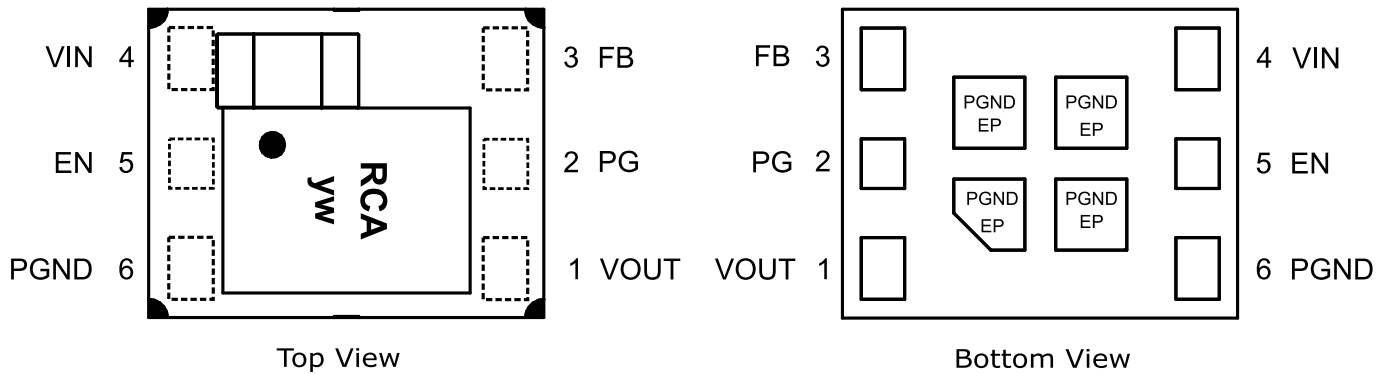


Figure 1: Pinout.

Table 1: Pin description.

SYMBOL	NUMBER	TYPE	DESCRIPTION
VOUT	1	Power	Output voltage. Place output capacitors as close as possible to VOUT and PGND. For thermal performance, use a copper plane at this pin.
PG	2	Output	Power good flag pin. This open drain output is pulled up if the feedback voltage is greater than 95% or less than 105% of the internal reference voltage. A pull-up resistor is required if this function is used.
FB	3	Input	Feedback pin. This pin must be connected to the external resistor divider (between VOUT and PGND) to adjust the output voltage.
VIN	4	Power	Input voltage pin. Place the input capacitor(s) as close as possible to VIN and PGND.
EN	5	Input	Enable pin. Pulling this pin high enables the device, while pulling this pin low shuts down the device. This pin must not be left floating.
PGND	6	Power	Power ground pin. This pin must be connected to the ground plane and to the thermal pad.
PGND	EP	Exposed Pad	Exposed pad. The exposed pad is internally electrically connected to PGND. It is recommended to connect it to the ground plane for optimal device heat dissipation.

## 2 ORDERING INFORMATION

Table 2: Ordering information.

ORDER CODE	SPECIFICATIONS	PACKAGE	PACKAGING UNIT
171010501	1A / 0.8V-5.5V Vout version	LGA-6EP	7" Reel (2000 pieces)
178010501	1A / 0.8V-5.5V Vout version	Eval Board	Box with 1 piece

## 3 SALES INFORMATION

Table 3: Sales information.

SALES CONTACT
Würth Elektronik eiSos GmbH & Co. KG EMC and Inductive Solutions Max-Eyth-Str. 1 74638 Waldenburg Germany Tel. +49 (0) 7942 945 0 <a href="http://www.we-online.com/powermodules">www.we-online.com/powermodules</a> Technical support: <a href="mailto:powermodules@we-online.com">powermodules@we-online.com</a>

#### 4 ABSOLUTE MAXIMUM RATINGS

**Caution:**

Exceeding the listed absolute maximum ratings may affect the device negatively and may cause permanent damage.

Table 4: Absolute maximum ratings.

SYMBOL	PARAMETER	LIMIT		UNIT
		MIN <sup>(1)</sup>	MAX <sup>(1)</sup>	
V <sub>IN</sub>	Input pin voltage	-0.3	6	V
V <sub>OUT</sub>	Output pin voltage	-0.3	V <sub>IN</sub> +0.3	V
FB	Feedback pin voltage	-0.3	V <sub>IN</sub> +0.3	V
EN	Enable pin voltage	-0.3	V <sub>IN</sub> +0.3	V
PG	Power good pin voltage	-0.3	V <sub>IN</sub> +0.3	V
T <sub>storage</sub>	Assembled, non-operating storage temperature	-40	125	°C
V <sub>esd</sub>	ESD Voltage (HBM), according to EN61000-4-2 <sup>(4)</sup>	-4	4	kV

#### 5 OPERATING CONDITIONS

Operating conditions are conditions under which the device is intended to be functional. All values are referenced to GND. MIN and MAX limits are valid for the recommended ambient temperature range of -40°C to 85°C.

Table 5: Operating conditions.

SYMBOL	PARAMETER	MIN <sup>(1)</sup>	TYP <sup>(3)</sup>	MAX <sup>(1)</sup>	UNIT
V <sub>IN</sub>	Input Voltage	2.5	-	5.5	V
V <sub>OUT</sub>	Output Voltage	0.8	-	5.5	V
T <sub>A</sub>	Ambient temperature range <sup>(2)</sup>	-40	-	85	°C
T <sub>jop</sub>	Junction temperature range	-40	-	125	°C
I <sub>out</sub>	Nominal output current <sup>(5)</sup>	-	-	1	A

#### 6 THERMAL SPECIFICATIONS

Table 6: Thermal specifications.

SYMBOL	PARAMETER	TYP <sup>(3)</sup>	UNIT
Θ <sub>JA</sub>	Junction-to-ambient thermal resistance <sup>(2)</sup>	110	K/W
T <sub>SD</sub>	Thermal shutdown, rising	160	°C
	Thermal shutdown, hysteresis	10	°C

## 7 ELECTRICAL SPECIFICATIONS

### Caution:

MIN and MAX limits are valid for the recommended ambient temperature range of -40°C to 85°C. Typical values represents statistically the utmost probable values at the following conditions:  $V_{IN} = 5V$ ,  $V_{OUT} = 1.8V$ ,  $C_{IN} = 4.7\mu F$  ceramic,  $C_{OUT} = 10\mu F$  ceramic,  $T_A = 25^\circ C$  unless otherwise noted.

Table 7: Electrical specifications part 1.

SYMBOL	PARAMETER	TEST CONDITIONS	MIN <sup>(1)</sup>	TYP <sup>(3)</sup>	MAX <sup>(1)</sup>	UNIT
<b>Output Current</b>						
$I_{OCP}$	Overcurrent limit		1.5	2.3	3.0	A
<b>Output Voltage</b>						
$V_{FB}$	Reference voltage		0.784	0.8	0.816	V
$I_{FB}$	Feedback pin bias current		-50	0	50	nA
$V_{OUT}$	Line regulation	$V_{IN} = V_{OUT} + 1V$ to 5.5V,	—	0.05	—	%
	Load regulation	$500mA \leq I_{LOAD} \leq 1A$	—	0.9	—	%
	Output voltage ripple	$V_{IN} = 3.6V$ , $I_{OUT} = 100mA$ , MODE = high, 20MHz BWL	—	6	—	mV <sub>pp</sub>
<b>Switching Frequency</b>						
$f_{SW}$	Switching frequency	COT operation	3.6	4	4.4	MHz
<b>Enable and Undervoltage Lockout</b>						
$V_{UVLO}$	$V_{IN}$ undervoltage threshold	$V_{IN}$ decreasing	2	2.1	2.2	V
		$V_{IN}$ undervoltage hysteresis	—	170	—	mV
$V_{EN}$	EN threshold	Enable logic high	1.2	—	—	V
		Enable logic low	—	—	0.4	V
$I_{EN}$	EN pin input current		-1	—	1	$\mu A$
<b>Input Quiescent and Shutdown Current</b>						
$I_{SD}$	Shutdown current	ENABLE = low	—	0.1	—	$\mu A$
$I_{IN}$	No load input current	$V_{OUT} = 3.3V$ , ENABLE = high, switching, no load	—	40	—	$\mu A$
		ENABLE = high, switching, no load	—	25	—	$\mu A$
$I_Q$	Quiescent current	ENABLE = high, no switching	—	22	—	$\mu A$
<b>Soft-Start</b>						
$t_{SS}$	Soft-start time	Rising edge to 95% of $V_{OUT}$	—	128	—	$\mu s$

## ELECTRICAL SPECIFICATIONS

### Caution:

MIN and MAX limits are valid for the recommended ambient temperature range of -40°C to 85°C. Typical values represents statistically the utmost probable values at the following conditions:  $V_{IN} = 5V$ ,  $V_{OUT} = 1.8V$ ,  $C_{IN} = 4.7\mu F$  ceramic,  $C_{OUT} = 10\mu F$  ceramic,  $T_A = 25^\circ C$  unless otherwise noted.


Table 8: Electrical specifications part 2.

SYMBOL	PARAMETER	TEST CONDITIONS	MIN <sup>(1)</sup>	TYP <sup>(3)</sup>	MAX <sup>(1)</sup>	UNIT
<b>Efficiency</b>						
$\eta$	Efficiency	$V_{IN} = 5V$ , $V_{OUT} = 3.3V$ , $I_{OUT} = 450mA$	—	92	—	%
		$V_{IN} = 3.6V$ , $V_{OUT} = 3.3V$ , $I_{OUT} = 200mA$	—	96	—	%
		$V_{IN} = 3.3V$ , $V_{OUT} = 2.5V$ , $I_{OUT} = 300mA$	—	93	—	%
<b>Power Good Output</b>						
$V_{LPG}$	PG low voltage	$R_{PG} = 10k\Omega$	—	—	0.4	V
$I_{OPG}$	PG open leakage current	$V_{PG} = 2.5V$	—	—	1	$\mu A$
$PG_{TH}$	PG threshold	Percentage of $V_{REF}$ at FB to indicate power good	—	95	—	%
$PG_{THHY}$	PG threshold hysteresis		—	3	—	%
$PG_{TDR}$	PG rise time		—	75	—	$\mu s$
$PG_{TDF}$	PG fall time		—	13	—	$\mu s$
<b>Output Capacitance</b>						
$C_{OUT\_MAX}$	Maximum output capacitance		—	220	—	$\mu F$



## 8 RoHS, REACH

Table 9: RoHS, REACH.

RoHS directive		Directive 2011/65/EU of the European Parliament and the Council of June 8th, 2011 on the restriction of the use of certain hazardous substances in electrical and electronic equipment.
REACH directive		Directive 1907/2006/EU of the European Parliament and the Council of June 1st, 2007 regarding the Registration, Evaluation, Authorization and Restriction of Chemicals (REACH).

## 9 PACKAGE SPECIFICATIONS

Table 10: Package specifications.

ITEM	PARAMETER	TYP <sup>(3)</sup>	UNIT
Lead finish	Silver-Palladium	—	—
Weight	—	0.0416	g

## 10 NOTES

- (1) Min and Max limits are 100% production tested at 25°C. Limits over the operating temperature range are guaranteed through correlation using Statistical Quality Control (SQC) methods.
- (2) Measured without heatsink, natural convection (0-20LFM / 0-0.1m/s) on the 178010501 evaluation board, a 40 x 40mm two layer board, with 35µm (1 ounce) copper.
- (3) Typical numbers are valid at 25°C ambient temperature and represent statistically the utmost probable values assuming a Gaussian distribution.
- (4) The human body model is a 100pF capacitor discharged through a 1.5Ωk resistor into each pin. Test method is per JESD-22-114.
- (5) Depending on ambient temperature; see [THERMAL DERATING](#).

## 11 TYPICAL PERFORMANCE CURVES

If not otherwise specified, the following conditions apply:  $V_{IN} = 5V$ ,  $V_{OUT} = 3.3V$ ,  $C_{IN} = 4.7\mu F$  X5R ceramic,  $C_{OUT} = 10\mu F$  X5R ceramic,  $C_{FF} = 22pF$ ,  $T_A = 25^\circ C$ .

### 11.1 RADIATED EMISSIONS EN55032 (CISPR-32) CLASS B COMPLIANT

Measured with module on an Evaluation Board 178010501 in a Fully Anechoic Room (FAR) at 3m antenna distance.

#### 11.1.1 TEST SETUP

Input wire length:

- Radiated Emission: 160cm (80cm Horizontal + 80cm Vertical)

Output wire length:

- Short wire (with input filter): Load directly on evaluation board
- Long wire (with input filter): 1m

**11.1.2 RADIATED EMISSIONS (Without Input Filter)**

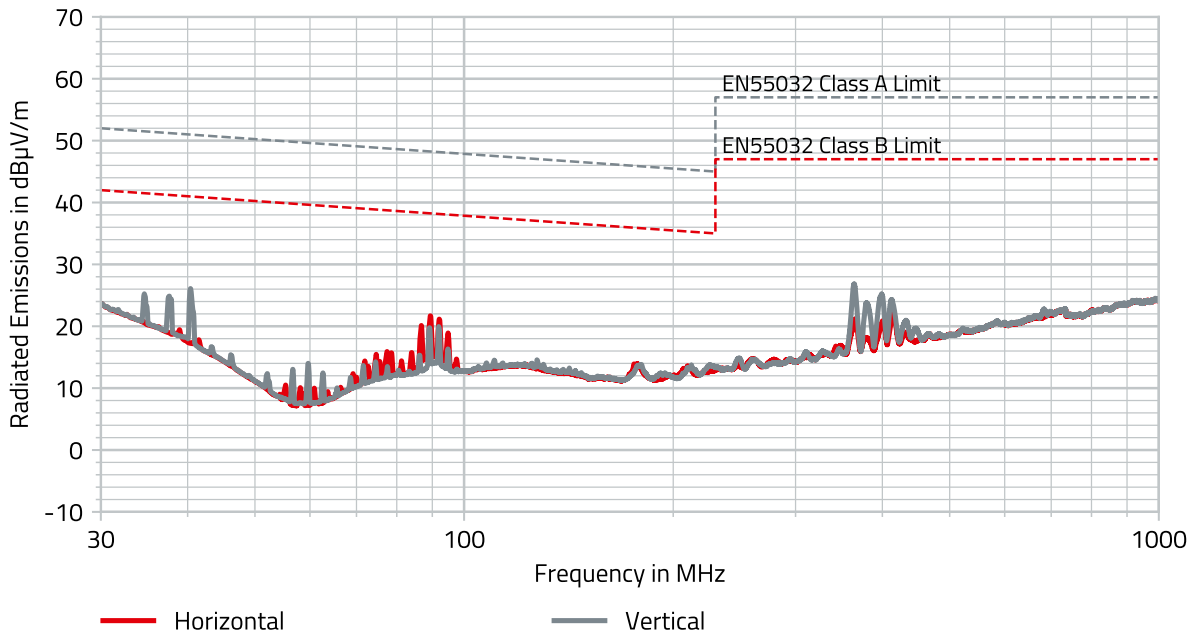


Figure 2: 171010501 radiated emissions (3m antenna distance)  $I_{OUT} = 1A$  without input filter

**11.1.3 RADIATED EMISSIONS (With Input Filter)**

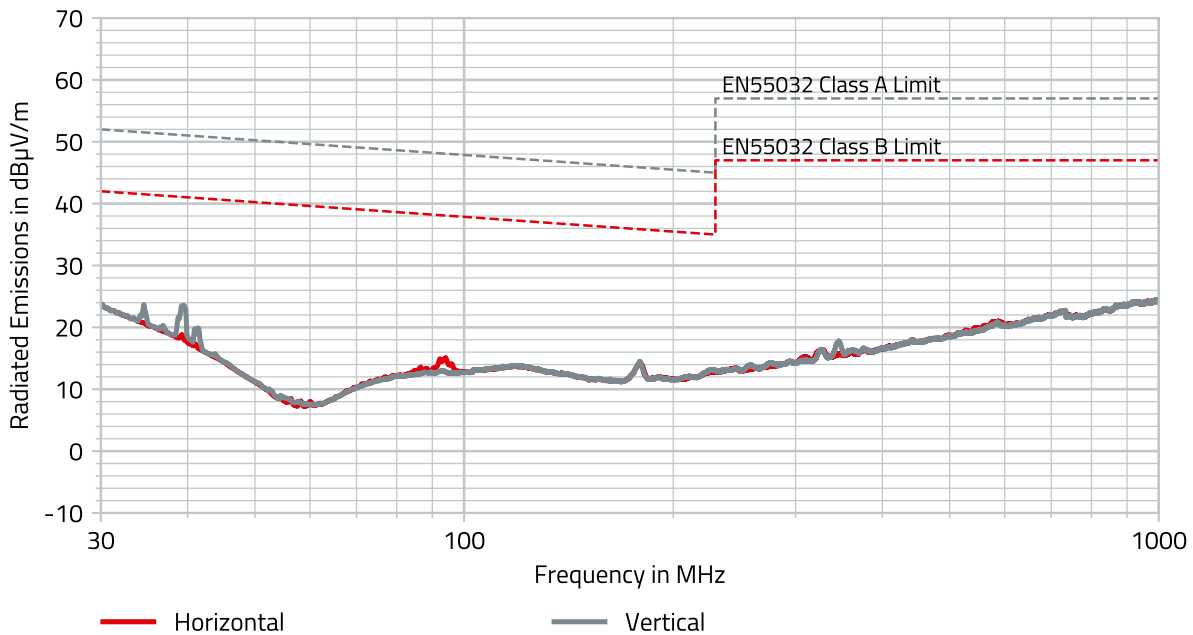


Figure 3: 171010501 radiated emissions (3m antenna distance)  $I_{OUT} = 1A$  with input filter

## 11.2 DC Performance Curves

### 11.2.1 Efficiency $5V_{IN}$

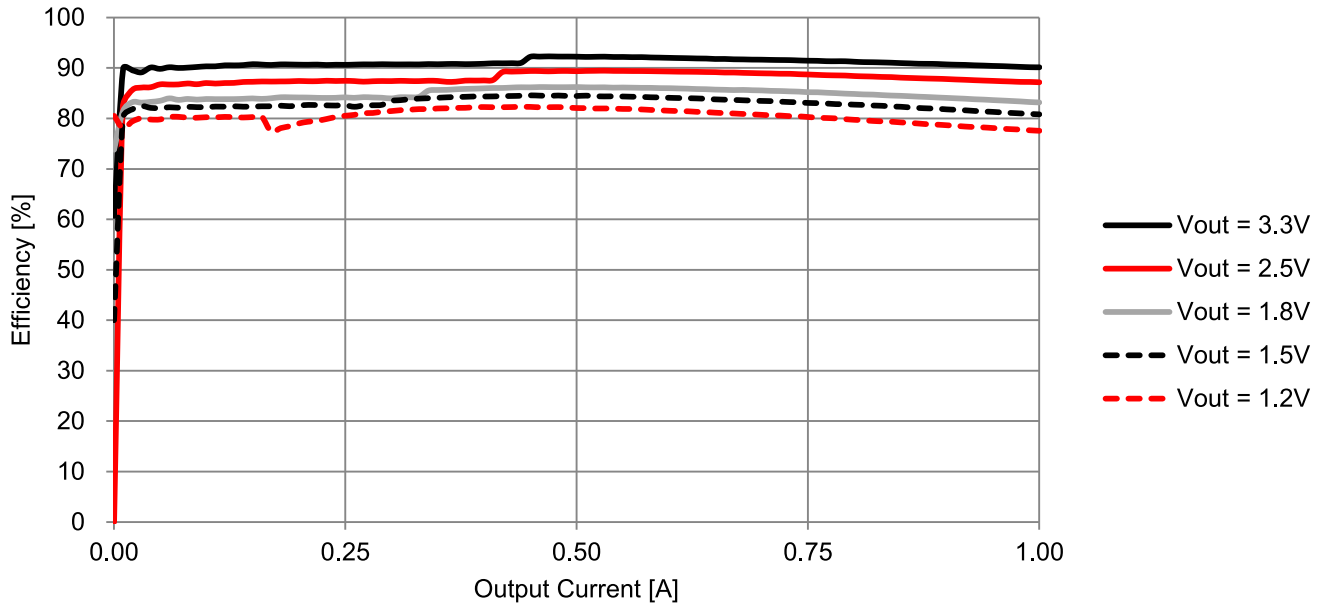


Figure 4: 171010501 efficiency  $V_{IN} = 5V$ .

### 11.2.2 Efficiency $3.6V_{IN}$

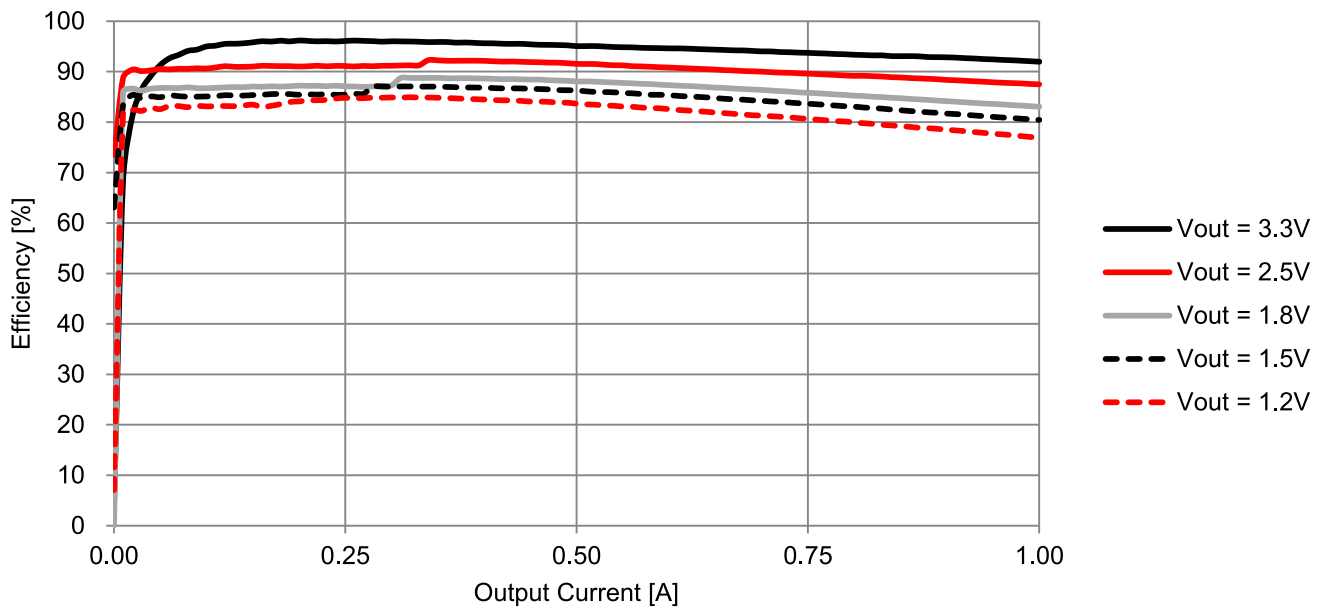
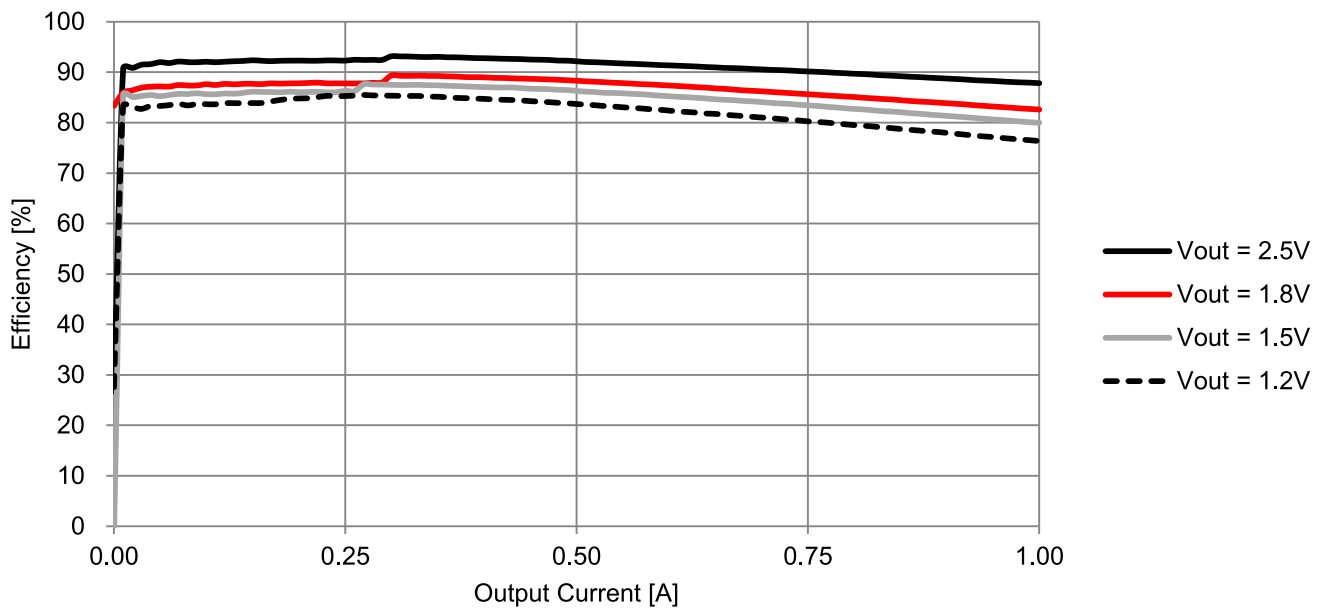


Figure 5: 171010501 efficiency  $V_{IN} = 3.6V$ .

11.2.3 Efficiency 3.3V<sub>IN</sub>Figure 6: 171010501 efficiency V<sub>IN</sub> = 3.3V.

### 11.2.4 Thermal Derating 5V<sub>IN</sub>

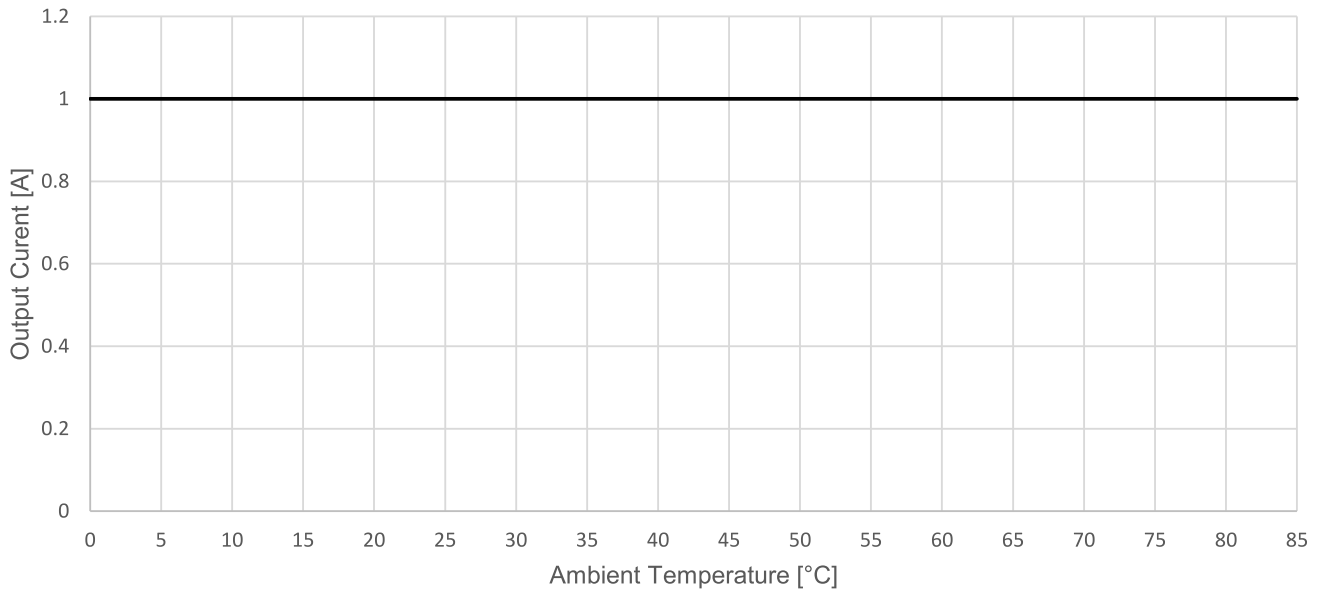


Figure 7: 171010501 output current thermal derating V<sub>IN</sub> = 5V.

### 11.2.5 Thermal Derating 3.6V<sub>IN</sub>

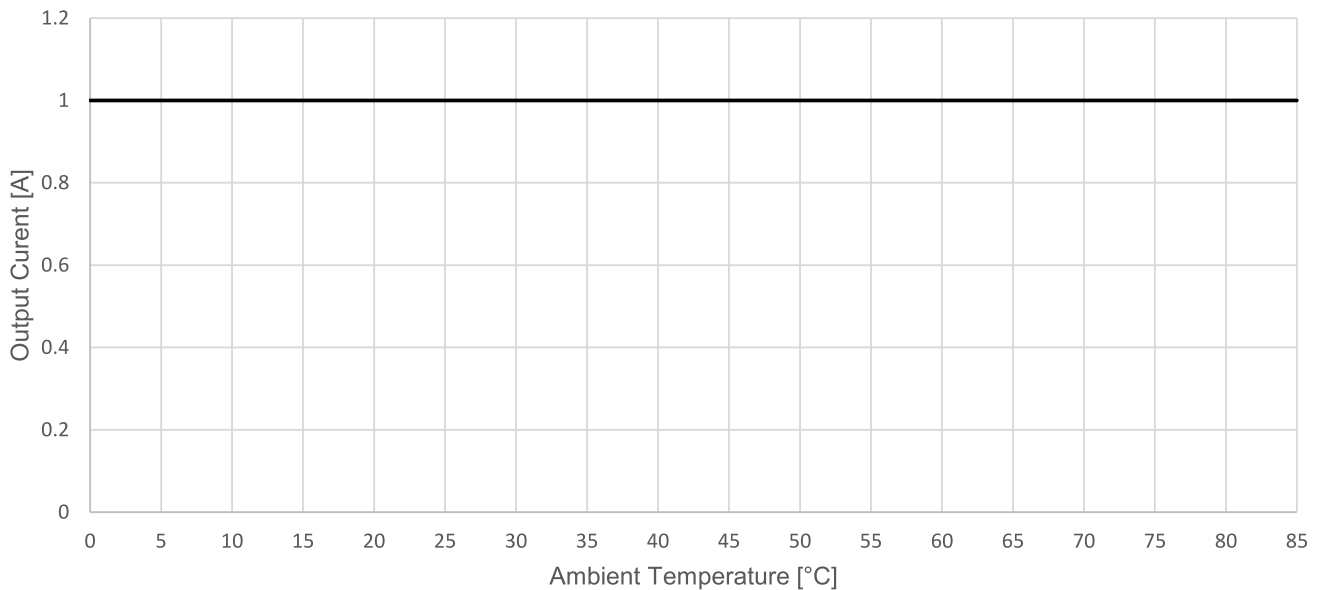


Figure 8: 171010501 output current thermal derating V<sub>IN</sub> = 3.6V.

Note: Both thermal derating graphs were measured on the 178010501 Evaluation Board (40 x 40mm two layer board, with 35µm (1 ounce) copper). Please see T<sub>A</sub> limits in [OPERATING CONDITIONS](#).

### 11.2.6 Load Regulation

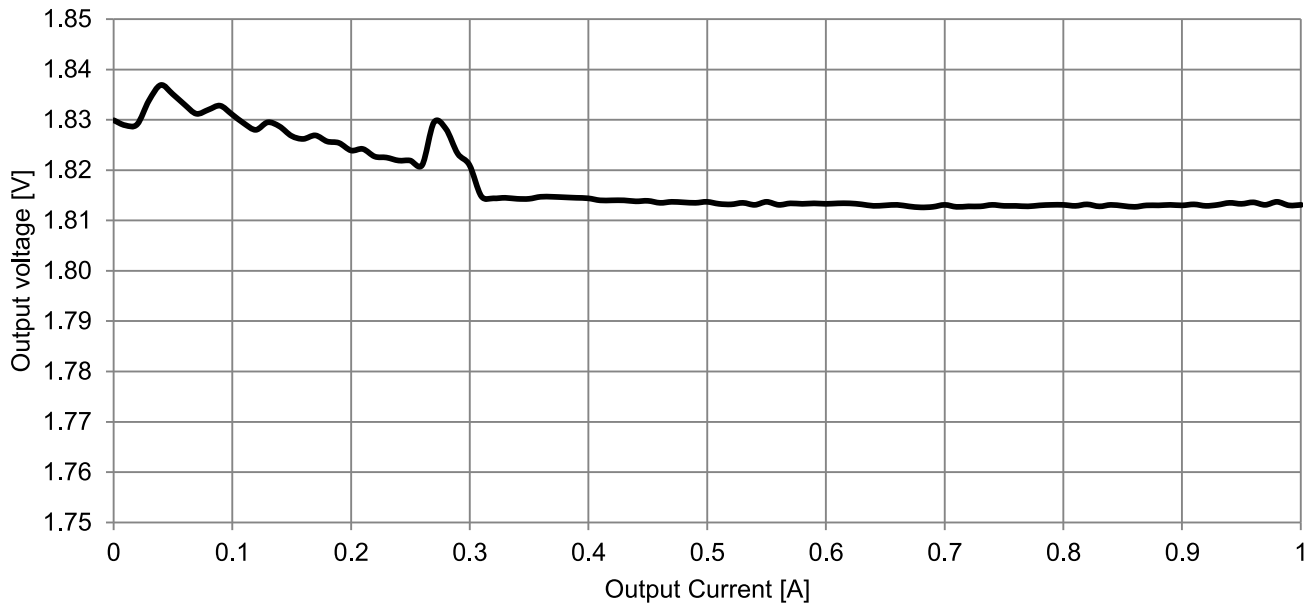


Figure 9: 171010501 load regulation  $V_{IN} = 3.6V$ ,  $V_{OUT} = 1.8V$ .

### 11.2.7 Line Regulation

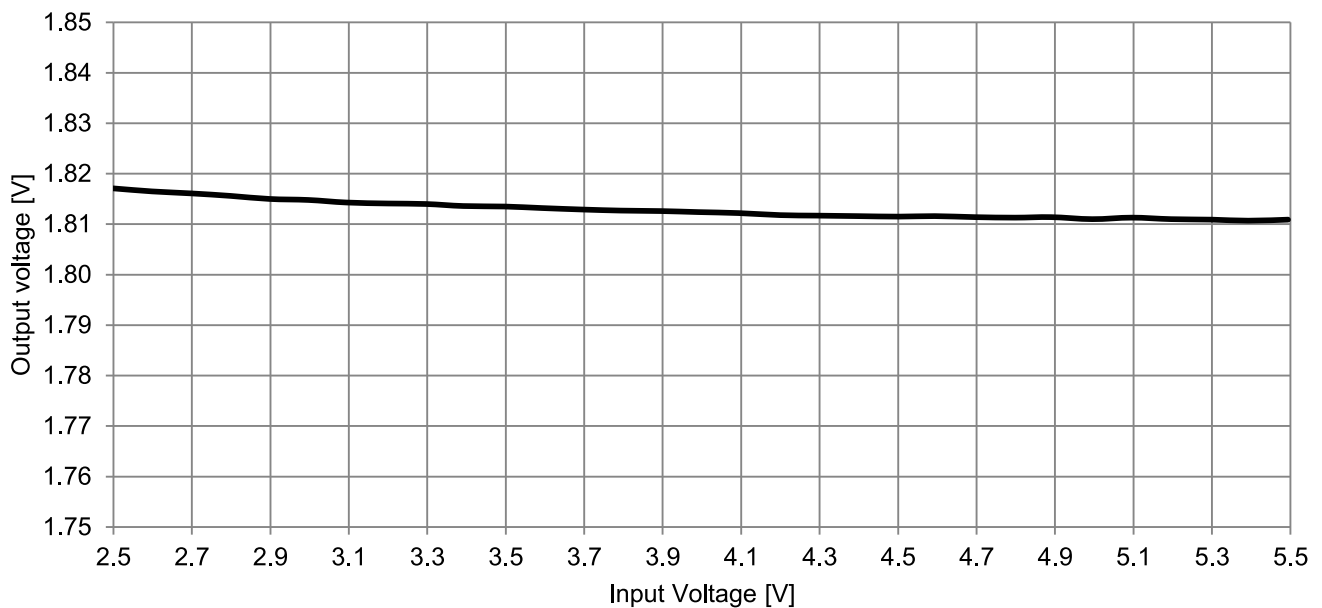


Figure 10: 171010501 line regulation  $V_{OUT} = 1.8V$ ,  $I_{OUT} = 1A$ .

## 12 BLOCK DIAGRAM

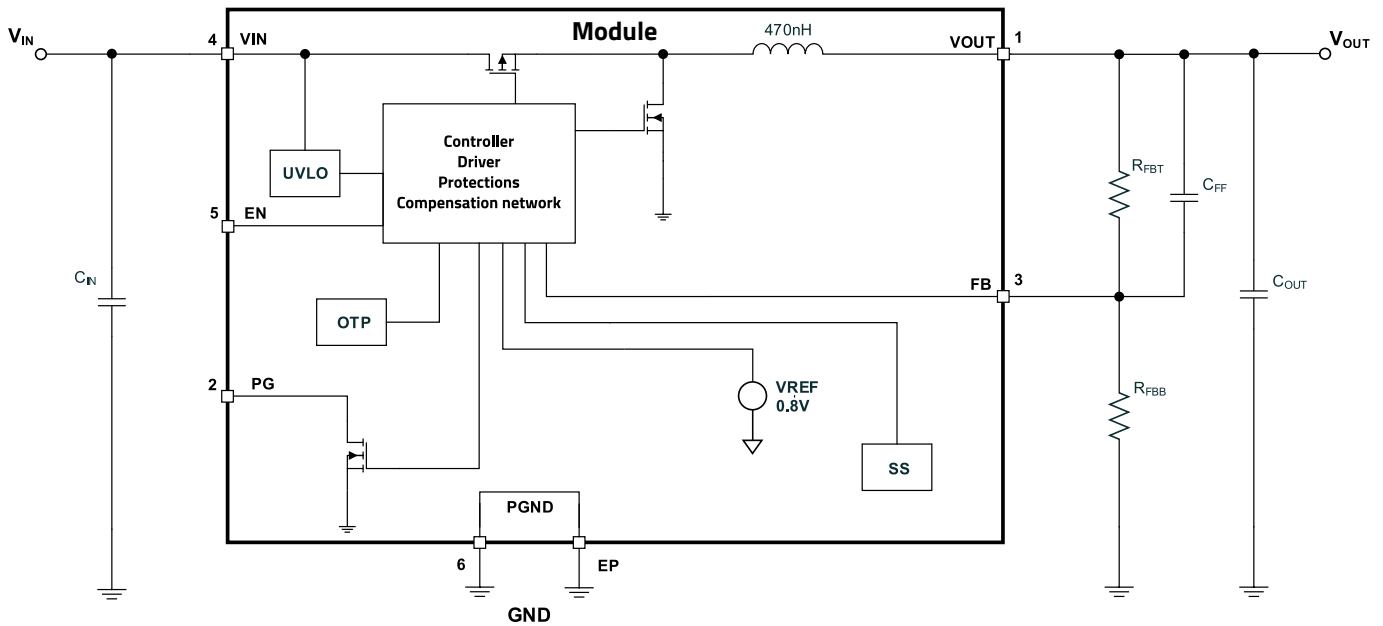


Figure 11: 171010501 block diagram.

## 13 CIRCUIT DESCRIPTION

The Magl<sup>3</sup>C power module 171010501 is a synchronous step down regulator with integrated MOSFETs, control circuitry and power inductor. The control scheme is based on a constant on-time (COT) regulation loop.

The  $V_{OUT}$  of the regulator is divided by the feedback resistor network  $R_{FBT}$  and  $R_{FBB}$  and fed into the FB pin. The internal comparator compares this signal with the internal 0.8V reference. If the feedback voltage is below the reference, the high side MOSFET is turned on for a fixed on-time.

The constant on-time control scheme does not require external compensation circuitry which makes the overall design very simple. Nevertheless, it requires a certain minimum ripple at the feedback pin. The Magl<sup>3</sup>C power module 171010501 generates this ripple internally and is supported by the  $C_{FF}$  capacitor which bypasses AC ripple directly to the feedback pin from the output. With this architecture very small output ripple values under  $10mV_{PP}$  (similar to current or voltage mode devices) can be achieved.



## 14 DESIGN FLOW

The following simple steps will show how to select the external components to design the 171010501 into an application.

### Essential Steps

1. Set output voltage
2. Select input capacitor
3. Select output capacitor
4. Select feed-forward capacitor

### Optional Steps

5. Set the power good resistor

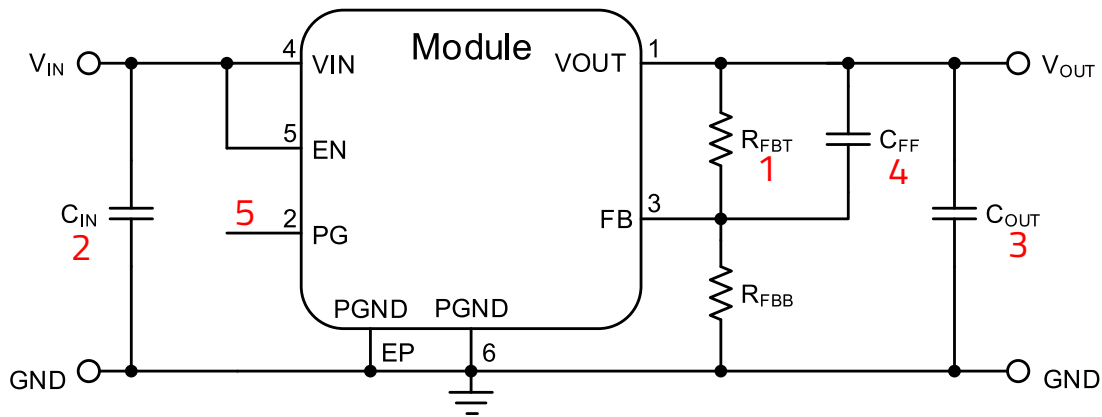


Figure 12: Design flow schematic.

#### 14.1 STEP 1 Setting The Output Voltage ( $V_{OUT}$ )

The output voltage is selected with an external resistor divider between  $V_{OUT}$  and GND (see circuit below). The voltage across the bottom resistor of the divider is provided to the FB pin and compared with an internal reference voltage of 0.8V ( $V_{REF}$ ). The output voltage adjustment range is from 0.8V to 5.5V. The output voltage can be calculated according to the following formula:

$$V_{OUT} = V_{REF} \cdot \left( \frac{R_{FBT}}{R_{FBB}} + 1 \right) \quad (1)$$

One resistor must be chosen and then the other resistor can be calculated. For example, if  $R_{FBT} = 100\text{k}\Omega$  then the resistance value of the lower resistor in the feedback network is indicated in the table below for common output voltages.

Table 11: Output voltage selection.

$V_{OUT}$ (V)	1.2	1.5	1.8	2.5	3.3	3.6	5
$R_{FBB}$ (E96) ( $\text{k}\Omega$ )	200	115	80.6	47.5	32.4	28.7	19.1

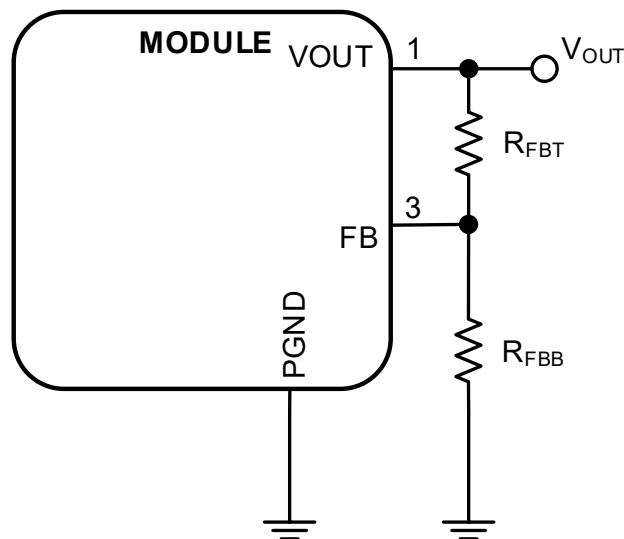


Figure 13: Output voltage schematic.

#### 14.2 STEP 2 Select The Input Capacitor (C<sub>IN</sub>)

An input capacitor of 4.7µF is integrated inside the 171010501 MagI<sup>3</sup>C power module, ensuring excellent EMI performance. An additional external input capacitance is required to provide the high input pulse current. The external input capacitor must be placed as close as possible to the VIN and PGND pins. For this MagI<sup>3</sup>C power module it is recommended to use an MLCC (multi-layer ceramic capacitor) of 4.7µF. Attention must be paid to the voltage, frequency, and temperature deratings as well as the thermal class of the selected capacitor. The Würth Elektronik part number 885012207053 has been experimentally verified to work with this power module.

#### 14.3 STEP 3 Select The Output Capacitor (C<sub>OUT</sub>)

The output capacitor should be selected in order to minimize the output voltage ripple and to provide a stable voltage at the output. It also affects the loop stability. An external MLCC of 10µF is recommended for all application conditions. Attention must be paid to the voltage, frequency, and temperature deratings as well as the thermal class of the selected capacitor. The Würth Elektronik part number 885012107014 has been experimentally verified to work with this power module.

In general, the output voltage ripple can be calculated using the following equation:

$$V_{\text{OUT ripple}} = \Delta I_L \cdot ESR + \Delta I_L \cdot \left( \frac{1}{8 \cdot f_{\text{SW}} \cdot C_{\text{OUT}}} \right) \quad (2)$$

where  $\Delta I_L$  is the inductor current ripple and can be calculated with the following equation:

$$\Delta I_L = \frac{V_{\text{OUT}} \cdot (V_{\text{IN}} - V_{\text{OUT}})}{f_{\text{SW}} \cdot L \cdot V_{\text{IN}}} \quad (3)$$

#### 14.4 STEP 4 Select The Feed-Forward Capacitor ( $C_{FF}$ )

The 171010501 Magl<sup>3</sup>C power module allows for the selection of a feed forward capacitor,  $C_{FF}$ , providing a trade-off between response time and efficiency while also affecting the transition current threshold between COT and PFM operation. A lower value of  $C_{FF}$  will increase the light load conversion efficiency while slowing down the response time and increasing the overshoot and undershoot. Increasing the  $C_{FF}$  value will decrease the response time and the overshoot and undershoot while decreasing light load conversion efficiency. Increasing the value of  $C_{FF}$  results in higher value of current needed to leave PFM operation.

A  $C_{FF}$  of 22pF has been evaluated experimentally as a value with suitable efficiency and transient characteristics for most applications. The Würth Elektronik part number 885012005009 has been experimentally verified to work with this power module.

The pictures below show the transient behavior of the 171010501 in response to a load transition from 0A to 1A using the recommended  $C_{FF} = 22\text{pF}$ , as well as other values of  $C_{FF}$ .

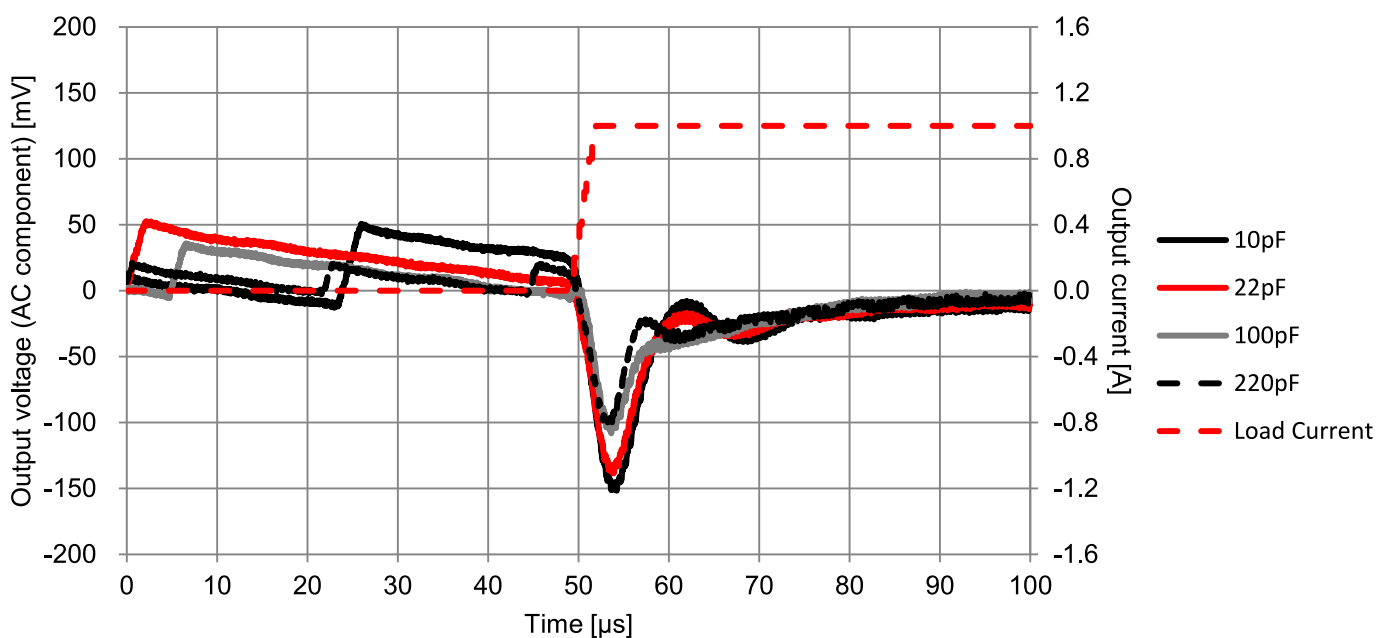


Figure 14: 171010501 load transient  $V_{IN} = 5\text{V}$ ,  $V_{OUT} = 1.8\text{V}$  from 0A to 1A.

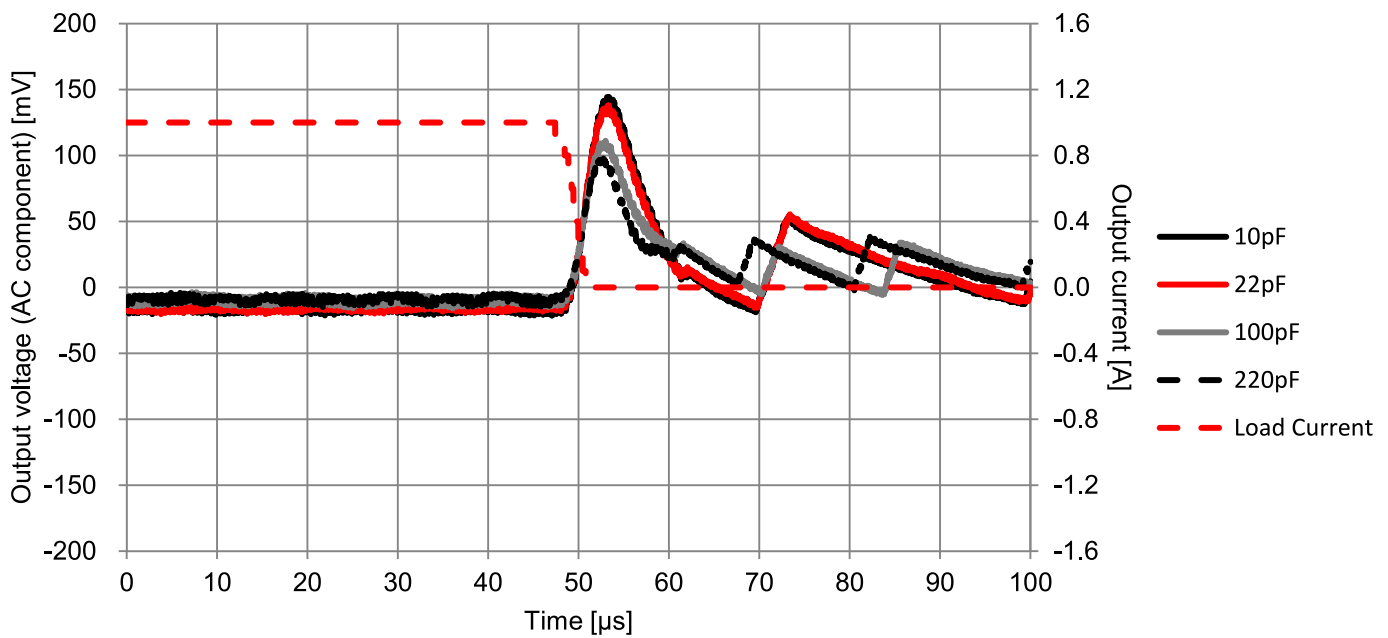


Figure 15: 171010501 load transient  $V_{IN} = 5V$ ,  $V_{OUT} = 1.8V$  from 1A to 0A.

These behaviors are valid only for the specified conditions and must be verified in the real application.

The  $C_{FF}$  value only affects the efficiency during light load conditions.

As explained in the section [MODES OF OPERATION](#), during light load conditions the device does not continuously switch, instead delivering energy to the load in bursts. The frequency between bursts is influenced by various parameters, including the  $C_{FF}$  value.

Increasing  $C_{FF}$  will cause the power module to burst more often, resulting in a decrease in light load efficiency.

While the recommended  $C_{FF}$  value of 22pF will work for most applications, the user can adjust the performance of the power module based on their application by trading between light load efficiency and transient response. This customization tailors the behavior of the power module to the application's needs. Any deviations from the recommended values and components should be thoroughly evaluated by the customer to ensure the device operates properly.

#### 14.5 STEP 5 Optional: Set the Power Good Resistor

The PG pin is an open-drain output. Once the output voltage is above 90% (typ.) of the internal reference voltage the PG pin transitions to a high impedance state. The recommended pull-up resistor value is  $1M\Omega$ , which should be connected to a voltage source such as  $V_{IN}$ . The PG pin is pulled low when the output voltage is lower than 90% (typ.) or higher than 120% (typ.) of the internal reference voltage. The PG pin will be pulled low when the UVLO or thermal shutdown activates or when the EN pin is pulled low.

## 15 MODES OF OPERATION

The power module will operate in one of four modes, depending on the operating conditions.

### 15.1 Constant On-Time (COT) Operation

The power module operates at a fixed switching frequency of 4MHz where the duty cycle (D) is determined by the following equation:

$$D = \frac{V_{OUT}}{V_{IN}} \quad (4)$$

The on-time is determined by the duty cycle and the switching frequency as follows:

$$t_{ON} = \frac{D}{f_{SW}} \quad (5)$$

The on and off-times can be related to the switching frequency as follows:

$$\frac{1}{f_{SW}} = t_{ON} + t_{OFF} \quad (6)$$

The mode of operation has a minimum off-time value of 60ns.

### 15.2 Fixed Off-Time Operation

When the minimum off-time of 60ns is reached and the duty cycle must increase further, the power module fixes the off-time to 60ns and begins increasing the on-time. This results in a decrease in switching frequency proportional to the increase in duty cycle.

### 15.3 100% Duty Cycle Operation

When the input voltage approaches the output voltage and the duty cycle approaches 100%, the power module will leave the high side MOSFET on continuously and the output voltage will be limited by the input voltage. Further decreases of input voltage will result in a corresponding decrease in output voltage.

### 15.4 Pulse Frequency Modulation (PFM) Operation

PFM operation is initiated when the power module enters discontinuous mode. A burst of switching cycles increases the output voltage above the set value followed by a period of dead time where the output current is only delivered by the output capacitor. This results in slightly increased output voltage ripple in exchange for significantly increased conversion efficiency.

## 16 OUTPUT VOLTAGE RIPPLE

The output voltage ripple is influenced by the duty cycle and the output current drawn from the module. If the MODE pin is pulled high and the duty cycle is below 76%, the ripple is very low and it always has the same frequency as the internal oscillator (4MHz typ.). If MODE is pulled low and either the load current is low enough or the duty cycle is high enough then the output voltage ripple will be higher and the frequency lower than the nominal switching frequency (see pictures below).

When the device approaches discontinuous mode it will automatically transition into PFM operation resulting in an increase in the output voltage ripple.

## 17 PROTECTION FEATURES

### 17.1 Overcurrent Protection (OCP)

For protection against load faults, the 171010501 MagI<sup>3</sup>C power module incorporates a cycle-by-cycle current limit (see  $I_{OCP}$  in [ELECTRICAL SPECIFICATIONS](#)). During switching, the output current is limited by turning off the high-side switch when the current limit value is detected. This switching behavior continues, limiting the on-time of the device until the overcurrent condition is removed. When the overcurrent condition is removed, normal switching behavior resumes.

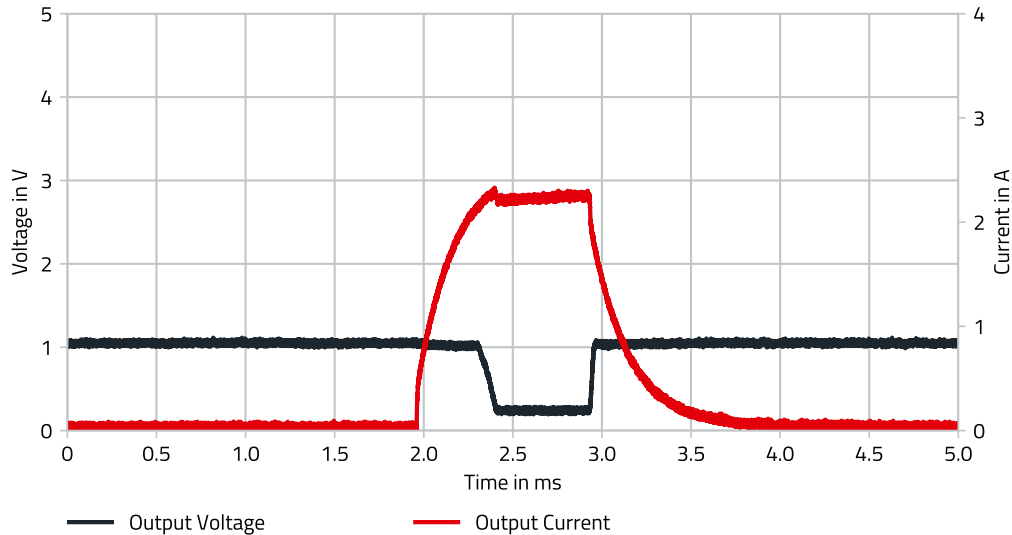


Figure 16: 171010501 overcurrent protection  $V_{IN} = 3.6V$ ,  $V_{OUT} = 1.8V$ ,  $I_{OUT} > 2A$ .

### 17.2 Short Circuit Protection (SCP)

When the 171010501 MagI<sup>3</sup>C power module experiences a short circuit condition at the output it will limit the current, typically to 2.2A, until the thermal protection circuit shuts the module off. If the short circuit condition is removed, normal switching operation will begin if the module temperature is not exceeding the thermal shutdown threshold.

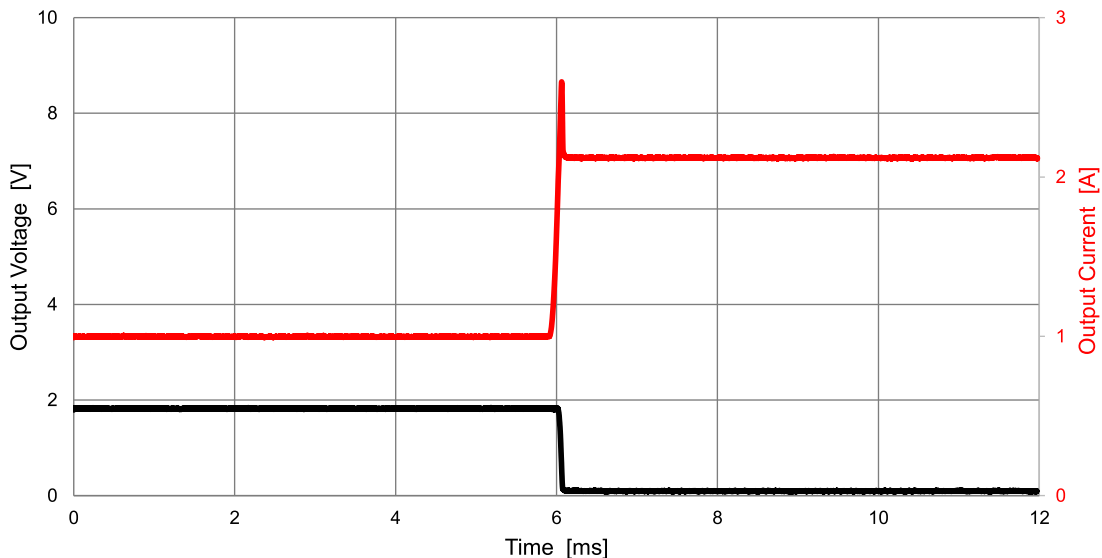


Figure 17: 171010501 short circuit protection  $V_{IN} = 3.6V$ ,  $V_{OUT} = 1.8V$ , short circuit at output.



### 17.3 Over Temperature Protection (OTP)

Thermal protection helps prevent catastrophic failures due to accidental device overheating. The junction temperature of the 171010501 Magi<sup>3</sup>C power module should not be allowed to exceed its maximum ratings. Thermal protection is implemented by an internal thermal shutdown circuit, which activates when the junction temperature reaches 160°C (typ). Under the thermal shutdown condition both MOSFETs remain off causing  $V_{OUT}$  to drop. When the junction temperature falls below the hysteric value, the internal soft-start is released,  $V_{OUT}$  rises smoothly, and normal operation resumes.

### 17.4 Undervoltage Lockout (UVLO)

The device incorporates input undervoltage lockout (UVLO) to protect from unexpected behavior at input voltages below the recommended values. The thresholds of the UVLO are indicated in the [ELECTRICAL SPECIFICATIONS](#).

### 17.5 Soft-Start

The 171010501 Magi<sup>3</sup>C power module implements an internal soft-start in order to limit the inrush current and avoid output voltage overshoot during start-up.

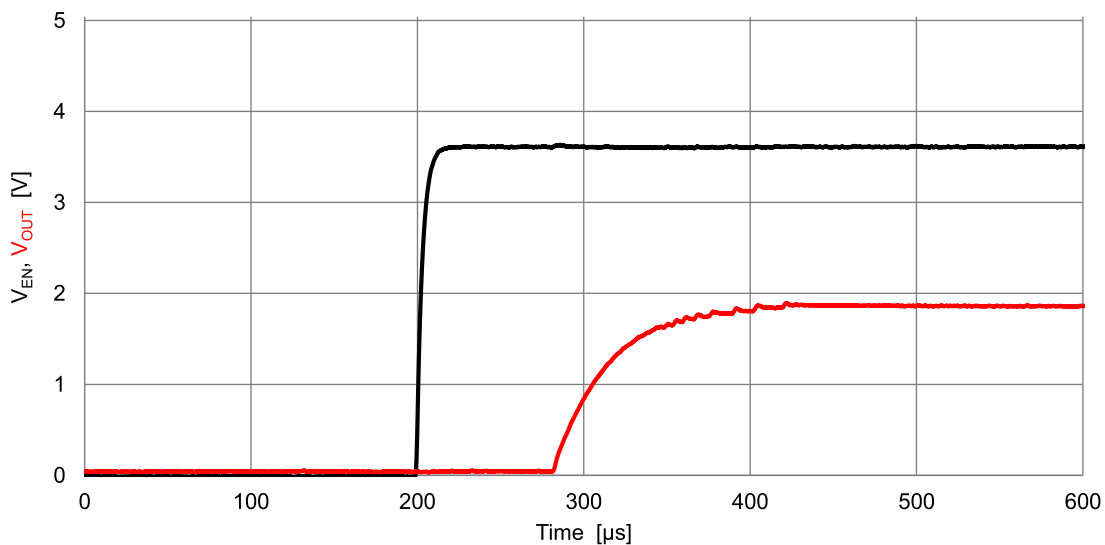


Figure 18: 171010501 soft-start  $V_{IN} = 3.6V$ ,  $V_{OUT} = 1.8V$ .

### 17.6 Enable

The 171010501 Magi<sup>3</sup>C power module is enabled by setting the pin EN high. After setting EN high the module prepares for operation. Once prepared, the module begins switching and the internal soft-start regulates the output voltage rise until the desired output voltage is met allowing normal operation to take place.

## 18 DESIGN EXAMPLE

### 18.1 Layout

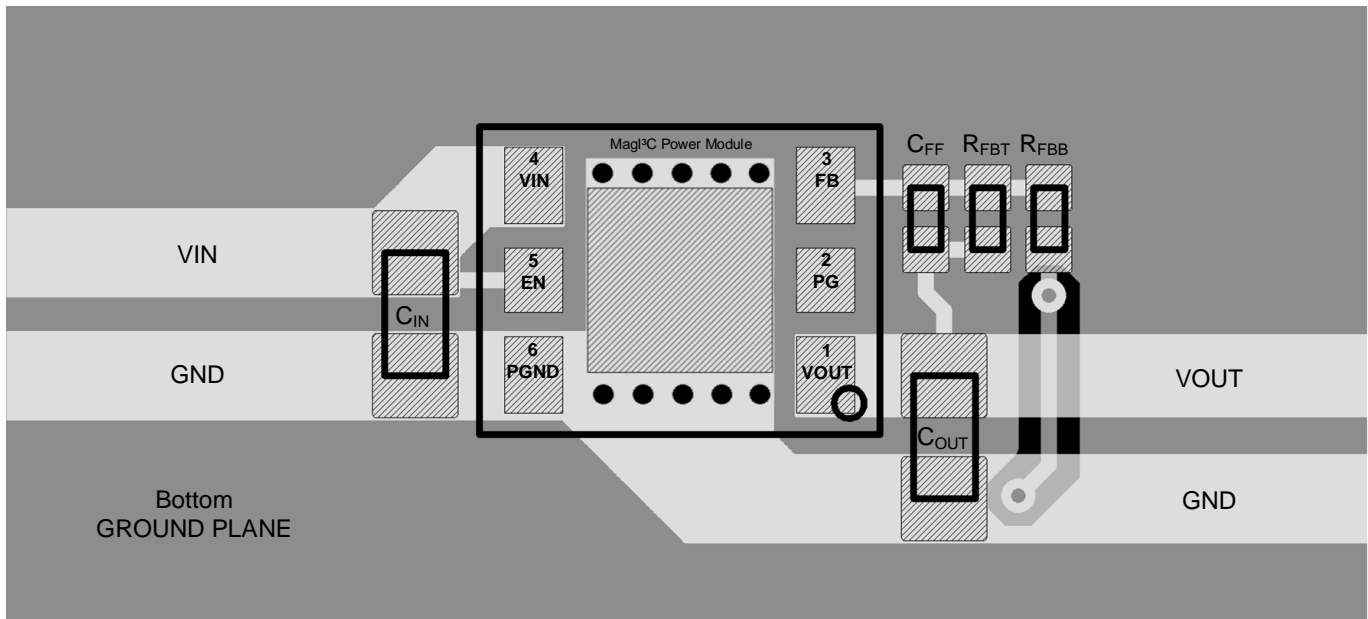


Figure 19: 171010501 layout recommendation.

The picture above shows a possible layout for the 171010501 MagI<sup>3</sup>C power module. Nevertheless, some recommendations should be followed when designing the layout:

1. The exposed pad should be connected to the bottom copper layer of the circuit board with sufficient vias to optimize the heat dissipation during operation. The above example uses 10 vias each with a drill diameter of 200µm. Ensure that nearby vias are either plugged or covered in solder mask to ensure the best solderability.
2. The input and output capacitors should be placed as close as possible to the VIN, VOUT and PGND pins of the device.
3. The feedback resistor divider should be placed as close as possible to the VOUT and FB pins.
4. Pins 5 (EN) must always be connected to either VIN or PGND and cannot be left floating (an example is shown in the layout depicted above, where EN is connected to VIN).

## 18.2 Schematic

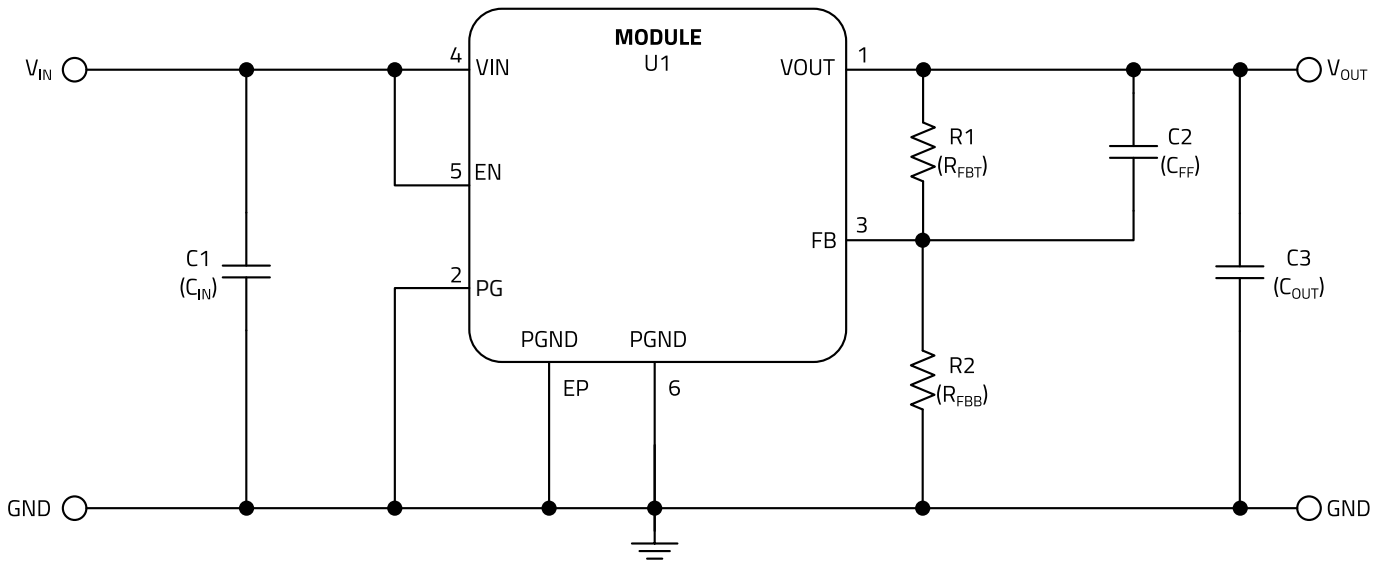


Figure 20: 171010501 design example schematic.

## 18.3 Bill of Materials

Table 12: 171010501 bill of materials.

Designator	Description	Quantity	Order Code	Manufacturer
U1	Magi <sup>3</sup> C power module	1	171010501	WE
C1, C3	Ceramic chip capacitor 10μF/16V X5R, 0805	2	885012107014	WE
C2	Ceramic chip capacitor 22pF/25V NPO, 0603	1	885012005009	WE
R1	100kΩ	1		
R2	49.9kΩ for V <sub>OUT</sub> = 1.8V	1		

## 19 HANDLING RECOMMENDATIONS

1. The power module is classified as MSL1 (JEDEC Moisture Sensitivity Level 1) according to JEDEC J-STD033.
2. The components should be sealed and stored in a controlled environment prior to soldering or other use.
3. If the components are to be baked prior to soldering, the baking must be performed with the components in an inert gas such as nitrogen or argon.
4. Maximum numbers of reflow cycles is two.
5. For minimum risk, solder the module in the last reflow cycle of the PCB production.
6. Please consider that the leads are finished with AgPd.
7. For solder paste use a standard SAC Alloy such as SAC 305, type 3 or higher.
8. The profile below is valid for convection reflow only.
9. Other soldering methods (e.g. vapor phase) are not verified and have to be validated by the customer at their own risk

## 20 SOLDERING PROFILE

Table 13: Reflow soldering profile.

Profile Feature	Symbol	Value
Preheat temperature minimum	$T_{s\_min}$	150°C
Preheat temperature maximum	$T_{s\_max}$	180°C
Preheat time from $T_{s\_min}$ to $T_{s\_max}$	$t_s$	60-90 seconds
Liquidous temperature	$T_L$	217°C
Time maintained above $T_L$	$t_L$	60-90 seconds
Classification temperature	$T_C$	240°C
Peak package body temperature	$T_P$	$T_P \leq T_C$
Time within $T_C - 5^\circ\text{C}$ and $T_C$	$t_p$	$t_p \leq 20$ seconds
Ramp-up Rate ( $T_L$ to $T_P$ )		3°C/second maximum
Ramp-down rate ( $T_P$ to $T_L$ )		3°C/second maximum
Time 25°C to peak temperature		8 minutes maximum

Please refer to JEDEC J-STD020E for further information pertaining to reflow soldering of electronic components.

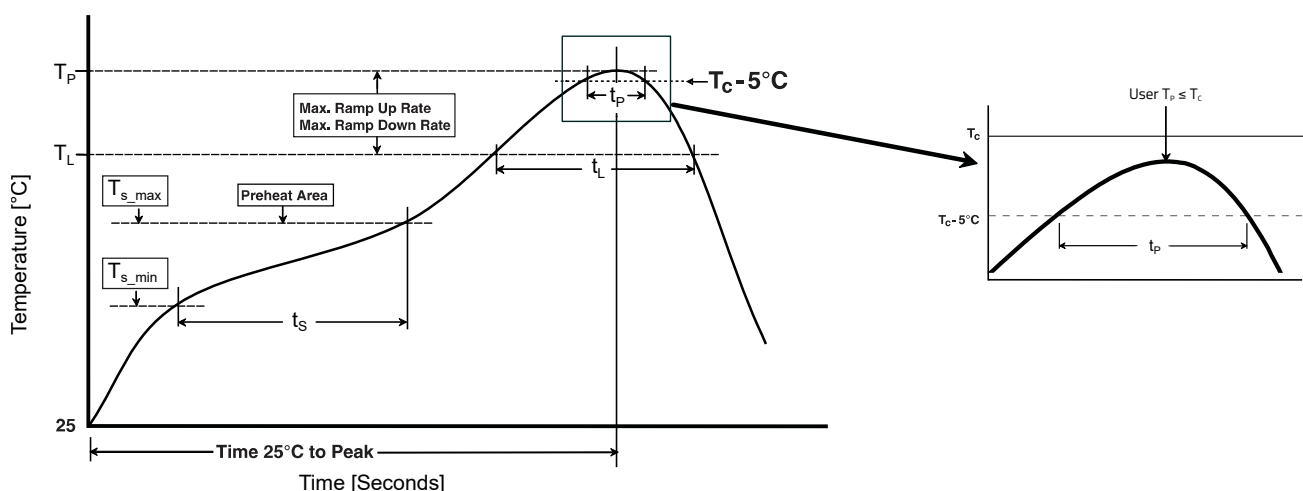
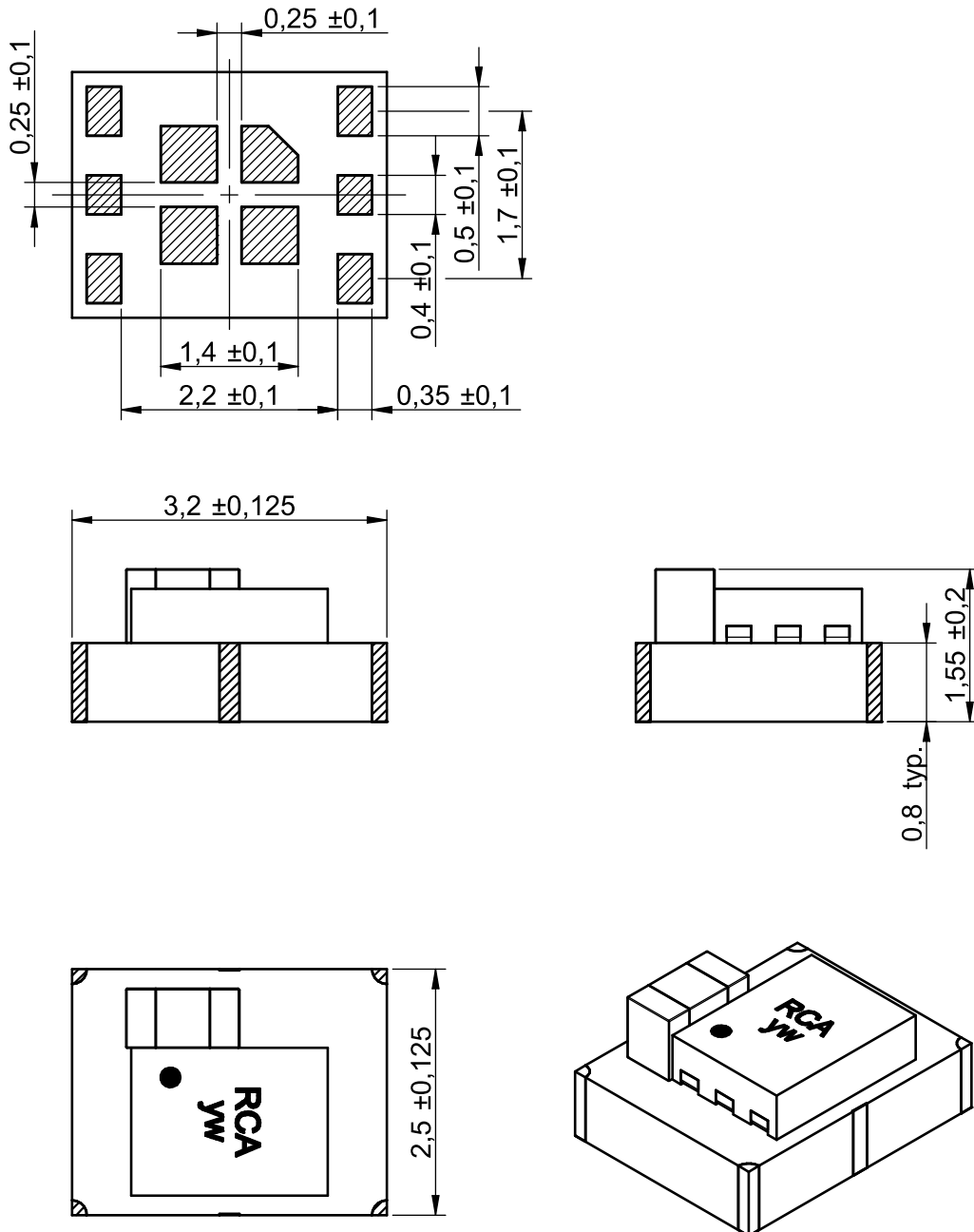


Figure 21: Soldering profile.

## 21 PHYSICAL DIMENSIONS

### 21.1 Component



All dimensions in mm  
 Tolerances  $\pm 0,1$ mm unless otherwise specified

## 21.2 Example Landpattern

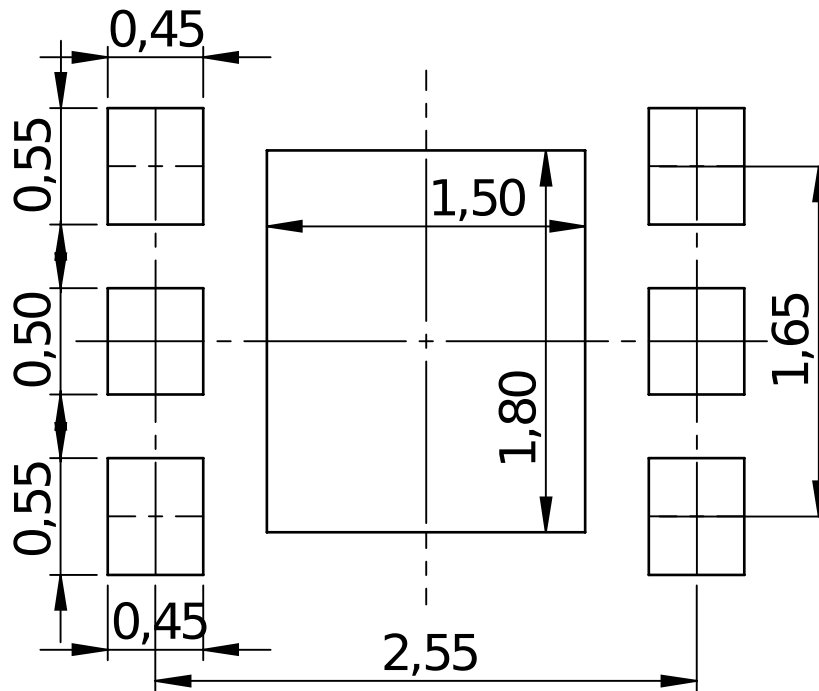


Figure 23: 171010501 example landpattern.

All dimensions in mm  
Stencil thickness of 100µm

21.3 Packaging

Reel in mm

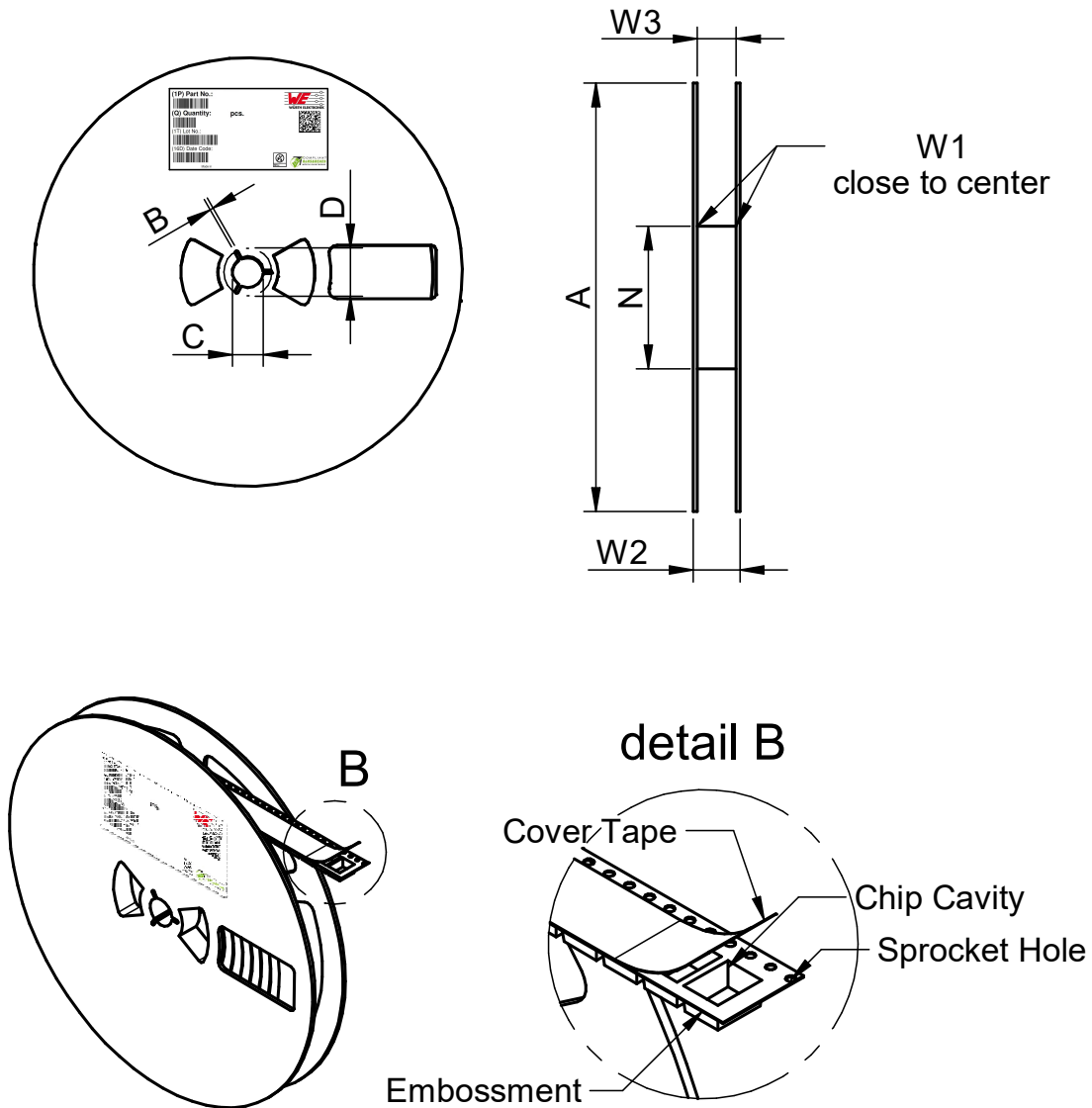


Figure 24: 171010501 reel dimensions.

Table 14: Reel dimensions.

A	B	C	D	N	W1	W2	W3	Material
Typ.	Min.	±0.8	Min.	Min.	±1.5	Max.	Min.	
178.00	1.5	13.00	20.20	50.00	8.40	14.40	7.90	Polystyrene

Tape in mm

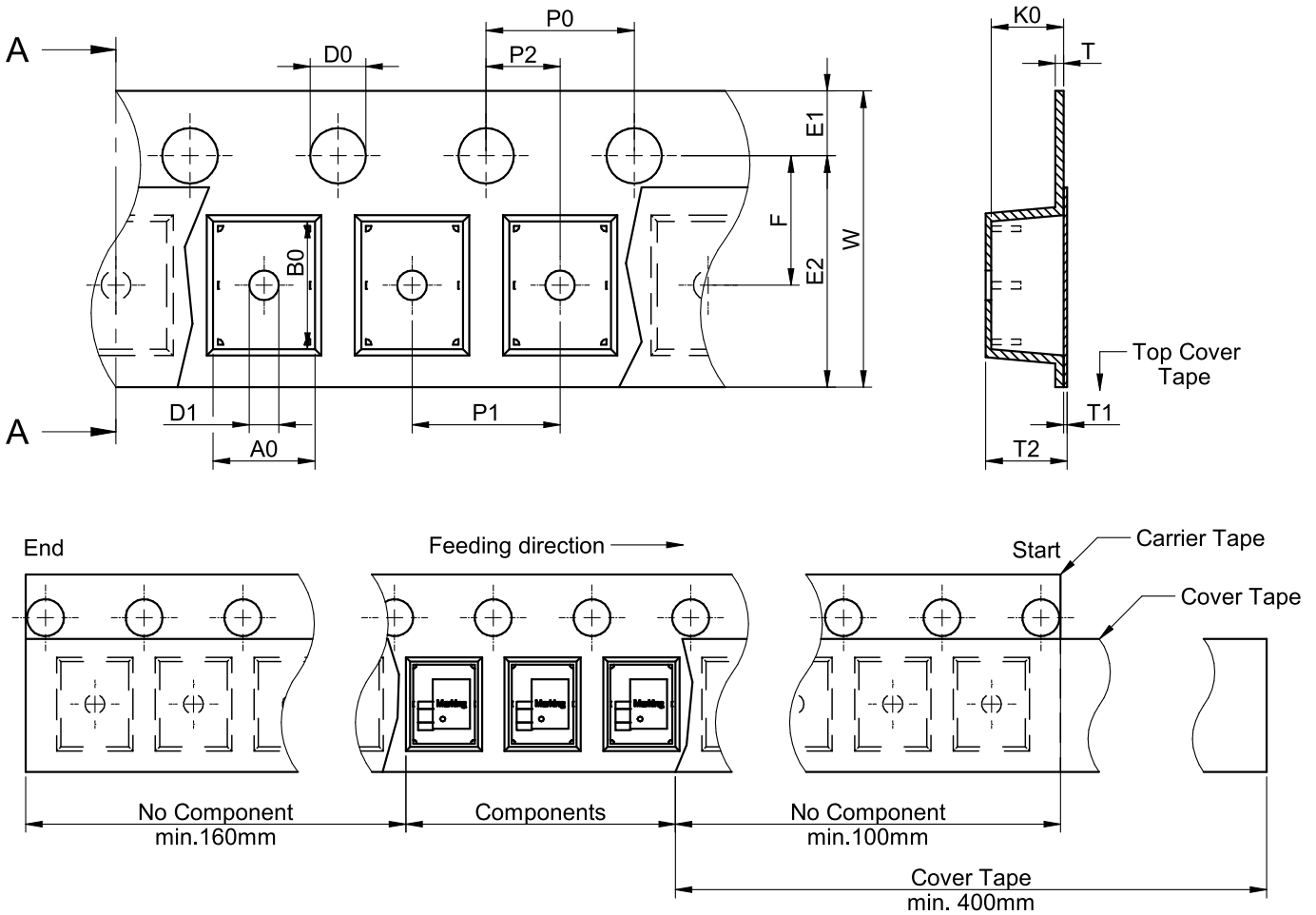


Figure 25: 171010501 tape dimensions.

A0	B0	W	T	T1	T2	D0	E1	E2	F	P0	P1	P2	Packaging Unit
±0.1	±0.1	±0.1	±0.1	±0.05	Max.	Typ.	±0.1	±0.1	Min.	±0.1	±0.1	±0.05	
2.75	3.45	8.00	4.00	0.22	0.10	2.20	1.50	1.75	6.25	3.50	4.00	2.00	2000

Tape material is polystyrene.



171010501

**MagI<sup>3</sup>C** Power Module

WPME-VDMM - Variable Step Down MicroModule

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## 22 DOCUMENT HISTORY

Table 15: Document history.

Revision	Date	Description	Comment
1.0	January 2020	Data sheet released	
2.0	August 2021	PCN	<p>Würth Elektronik has added the maximum allowable output capacitance that can be used at the output of the power module. Würth Elektronik has updated:</p> <ul style="list-style-type: none"> <li>▪ The minimum and maximum storage temperature (page 4).</li> <li>▪ The junction to ambient thermal resistance (page 4).</li> <li>▪ The pin ESD voltage ratings (page 4).</li> <li>▪ The layout recommendation to improve readability and recommended practices (page 26).</li> <li>▪ The solder handling instructions (no change to actual profile) (page 28).</li> <li>▪ The evaluation board bill of material to reflect the evaluation board (page 27).</li> <li>▪ The cautions and warnings of the data sheet (page 34).</li> <li>▪ The package and packaging drawings (page 29).</li> <li>▪ The format of the data sheet to improve readability of the document.</li> </ul>
2.1	June 2022	Minor update	Corrected pinout drawing by moving exposed pad notch (page 2).
3.0	September 2024	PCN	<p>Würth Elektronik has updated or corrected:</p> <ul style="list-style-type: none"> <li>▪ Line and load regulation units.</li> <li>▪ Input current values.</li> <li>▪ Modes of operation.</li> <li>▪ Overcurrent graph.</li> <li>▪ Handling recommendations.</li> <li>▪ MSL level.</li> <li>▪ Number of allowed solder cycles.</li> <li>▪ Component storage and baking instructions.</li> <li>▪ Block diagram.</li> <li>▪ Absolute maximum voltage values.</li> <li>▪ Resistor value for 5V in design flow.</li> </ul>

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## 25 CAUTIONS AND WARNINGS

The following conditions apply to all goods within the product series of MagI<sup>3</sup>C of Würth Elektronik eiSos GmbH & Co. KG:

### General:

- All recommendations according to the general technical specifications of the data-sheet have to be complied with.
- The usage and operation of the product within ambient conditions which probably alloy or harm the component surface has to be avoided.
- The responsibility for the applicability of customer specific products and use in a particular customer design is always within the authority of the customer. All technical specifications for standard products do also apply for customer specific products
- Residual washing varnish agent that is used during the production to clean the application might change the characteristics of the body, pins or termination. The washing varnish agent could have a negative effect on the long term function of the product. Direct mechanical impact to the product shall be prevented as the material of the body, pins or termination could flake or in the worst case it could break. As these devices are sensitive to electrostatic discharge customer shall follow proper IC Handling Procedures.
- Customer acknowledges and agrees that it is solely responsible for compliance with all legal, regulatory and safety-related requirements concerning its products, and any use of Würth Elektronik eiSos GmbH & Co. KG components in its applications, notwithstanding any applications-related information or support that may be provided by Würth Elektronik eiSos GmbH & Co. KG.
- Customer represents and agrees that it has all the necessary expertise to create and implement safeguards which anticipate dangerous consequences of failures, monitor failures and their consequences lessen the likelihood of failures that might cause harm and take appropriate remedial actions
- Customer will fully indemnify Würth Elektronik eiSos and its representatives against any damages arising out of the use of any Würth Elektronik eiSos GmbH & Co. KG components in safety-critical applications

### Product specific:

Follow all instructions mentioned in the datasheet, especially:

- The solder profile has to comply with the technical reflow or wave soldering specification, otherwise this will void the warranty.
- All products are supposed to be used before the end of the period of 12 months based on the product date-code.
- Violation of the technical product specifications such as exceeding the absolute maximum ratings will void the warranty.
- It is also recommended to return the body to the original moisture proof bag and reseal the moisture proof bag again.
- ESD prevention methods need to be followed for manual handling and processing by machinery.

### Disclaimer:

This electronic component has been designed and developed for usage in general electronic equipment only. This product is not authorized for use in equipment where a higher safety standard and reliability standard is especially required or where a failure of the product is reasonably expected to cause severe personal injury or death, unless the parties have executed an agreement specifically governing such use. Moreover Würth Elektronik eiSos GmbH & Co. KG products are neither designed nor intended for use in areas such as military, aerospace, aviation, nuclear control, submarine, transportation (automotive control, train control, ship control), transportation signal, disaster prevention, medical, public information network etc. Würth Elektronik eiSos GmbH & Co. KG must be informed about the intent of such usage before the design-in stage. In addition, sufficient reliability evaluation checks for safety must be performed on every electronic component which is used in electrical circuits that require high safety and reliability functions or performance. These cautions and warnings comply with the state of the scientific and technical knowledge and are believed to be accurate and reliable. However, no responsibility is assumed for inaccuracies or incompleteness.

## 26 IMPORTANT NOTES

### General Customer Responsibility

Some goods within the product range of Würth Elektronik eiSos GmbH & Co. KG contain statements regarding general suitability for certain application areas. These statements about suitability are based on our knowledge and experience of typical requirements concerning the areas, serve as general guidance and cannot be estimated as binding statements about the suitability for a customer application. The responsibility for the applicability and use in a particular customer design is always solely within the authority of the customer. Due to this fact it is up to the customer to evaluate, where appropriate to investigate and decide whether the device with the specific product characteristics described in the product specification is valid and suitable for the respective customer application or not. Accordingly, the customer is cautioned to verify that the datasheet is current before placing orders.

### Customer Responsibility Related to Specific, in Particular Safety-Relevant, Applications

It has to be clearly pointed out that the possibility of a malfunction of electronic components or failure before the end of the usual lifetime cannot be completely eliminated in the current state of the art, even if the products are operated within the range of the specifications. In certain customer applications requiring a very high level of safety and especially in customer applications in which the malfunction or failure of an electronic component could endanger human life or health it must be ensured by most advanced technological aid of suitable design of the customer application that no injury or damage is caused to third parties in the event of malfunction or failure of an electronic component.

### Best Care and Attention

Any product-specific notes, warnings and cautions must be strictly observed. Any disregard will result in the loss of warranty.

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### Product R&D

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### Product Life Cycle

Due to technical progress and economical evaluation we also reserve the right to discontinue production and delivery of products. As a standard reporting procedure of the Product Termination Notification (PTN) according to the JEDEC Standard we will inform at an early stage about inevitable product discontinuance. According to this we cannot guarantee that all products within our product range will always be available. Therefore it needs to be verified with the field sales engineer or the internal sales person in charge about the current product availability expectancy before or when the product for application design-in disposal is considered. The approach named above does not apply in the case of individual agreements deviating from the foregoing for customer-specific products.

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